

## 1. General description

Planar passivated high commutation three quadrant triac in a SOT78 (TO-220AB) plastic package intended for use in circuits where high static and dynamic dV/dt and high di/dt can occur. This "series CT" triac will commutate the full RMS current at the maximum rated junction temperature ( $T_{j(max)} = 150^\circ\text{C}$ ) without the aid of a snubber. It is used in applications where "high junction operating temperature capability" is required.

## 2. Features and benefits

- 3Q technology for improved noise immunity
- High commutation capability with maximum false trigger immunity
- High immunity to false turn-on by dV/dt
- High junction operating temperature capability
- High voltage capability
- Less sensitive gate for high noise immunity
- Planar passivated for voltage ruggedness and reliability
- Triggering in three quadrants only

## 3. Applications

- Applications subject to high temperature
- Electronic thermostats (heating and cooling)
- Motor controls e.g. washing machines and vacuum cleaners
- Rectifier-fed DC inductive loads e.g. DC motors and solenoids

## 4. Quick reference data

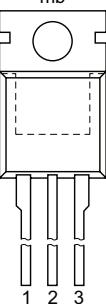
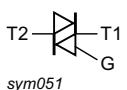
Table 1. Quick reference data

Symbol	Parameter	Conditions		Min	Typ	Max	Unit
$V_{DRM}$	repetitive peak off-state voltage			-	-	800	V
$I_{T(RMS)}$	RMS on-state current	full sine wave; $T_{mb} \leq 131^\circ\text{C}$ ; <a href="#">Fig. 1</a> ; <a href="#">Fig. 2</a> ; <a href="#">Fig. 3</a>		-	-	10	A
$I_{TSM}$	non-repetitive peak on-state current	full sine wave; $T_{j(init)} = 25^\circ\text{C}$ ; $t_p = 20\text{ ms}$ ; <a href="#">Fig. 4</a> ; <a href="#">Fig. 5</a>		-	-	100	A

Symbol	Parameter	Conditions		Min	Typ	Max	Unit
<b>Static characteristics</b>							
I <sub>GT</sub>	gate trigger current	V <sub>D</sub> = 12 V; I <sub>T</sub> = 0.1 A; T2+ G+ T <sub>j</sub> = 25 °C; <a href="#">Fig. 7</a>		2	-	35	mA
		V <sub>D</sub> = 12 V; I <sub>T</sub> = 0.1 A; T2+ G- T <sub>j</sub> = 25 °C; <a href="#">Fig. 7</a>		2	-	35	mA
		V <sub>D</sub> = 12 V; I <sub>T</sub> = 0.1 A; T2- G- T <sub>j</sub> = 25 °C; <a href="#">Fig. 7</a>		2	-	35	mA
<b>Dynamic characteristics</b>							
dV <sub>D</sub> /dt	rate of rise of off-state voltage	V <sub>DM</sub> = 536 V; T <sub>j</sub> = 150 °C; (V <sub>DM</sub> = 67% of V <sub>DRM</sub> ); exponential waveform; gate open circuit		500	-	-	V/μs
dI <sub>com</sub> /dt	rate of change of commutating current	V <sub>D</sub> = 400 V; T <sub>j</sub> = 150 °C; I <sub>T(RMS)</sub> = 10 A; dV <sub>com</sub> /dt = 20 V/μs; (snubberless condition); gate open circuit		8	-	-	A/ms

## 5. Pinning information

Table 2. Pinning information

Pin	Symbol	Description	Simplified outline	Graphic symbol
1	T1	main terminal 1		
2	T2	main terminal 2		
3	G	gate		
mb	T2	mounting base; main terminal 2		 sym051

## 6. Ordering information

Table 3. Ordering information

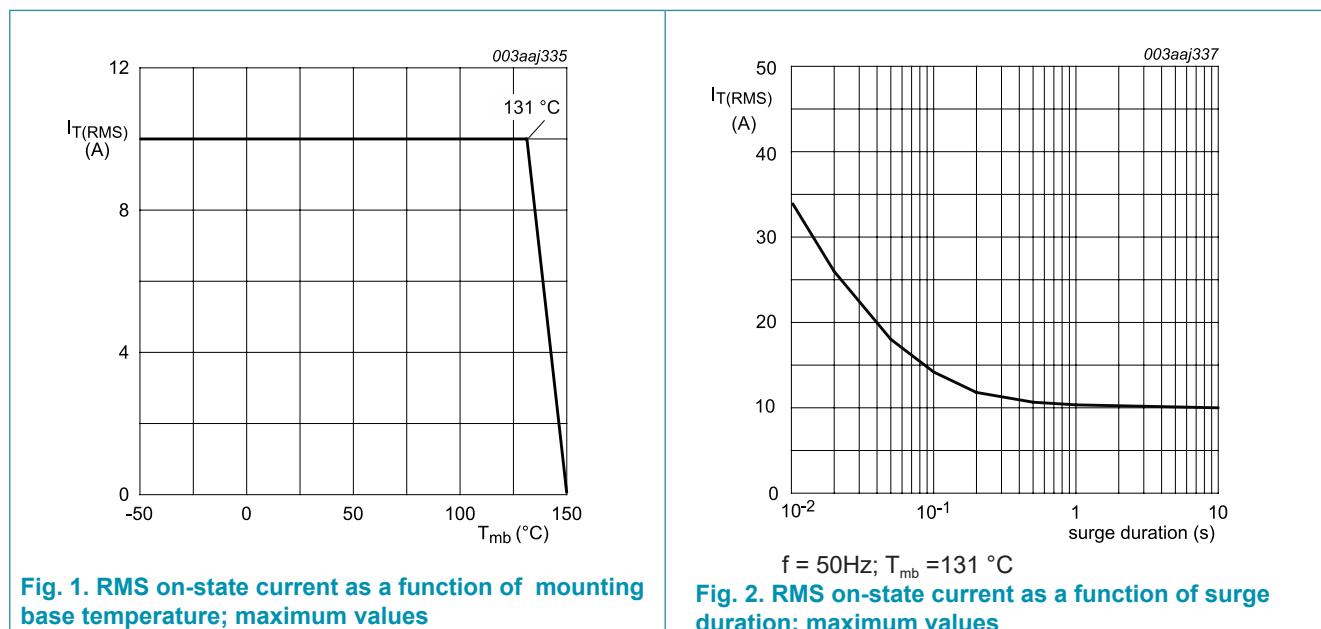
Type number	Package		Version
	Name	Description	
BTA410-800CT	TO-220AB	plastic single-ended package; heatsink mounted; 1 mounting hole; 3-lead TO-220AB	SOT78

## 7. Limiting values

**Table 4. Limiting values**

In accordance with the Absolute Maximum Rating System (IEC 60134).

Symbol	Parameter	Conditions		Min	Max	Unit
$V_{DRM}$	repetitive peak off-state voltage			-	800	V
$I_{T(RMS)}$	RMS on-state current	full sine wave; $T_{mb} \leq 131^\circ\text{C}$ ; <a href="#">Fig. 1</a> ; <a href="#">Fig. 2</a> ; <a href="#">Fig. 3</a>		-	10	A
$I_{TSM}$	non-repetitive peak on-state current	full sine wave; $T_{j(init)} = 25^\circ\text{C}$ ; $t_p = 20\text{ ms}$ ; <a href="#">Fig. 4</a> ; <a href="#">Fig. 5</a>		-	100	A
		full sine wave; $T_{j(init)} = 25^\circ\text{C}$ ; $t_p = 16.7\text{ ms}$		-	110	A
$I^2t$	$I^2t$ for fusing	$t_p = 10\text{ms}$ ; sine-wave pulse		-	50	$\text{A}^2\text{s}$
$dI/dt$	rate of rise of on-state current	$I_G = 70\text{ mA}$		-	100	$\text{A}/\mu\text{s}$
$I_{GM}$	peak gate current			-	2	A
$P_{GM}$	peak gate power			-	5	W
$P_{G(AV)}$	average gate power	over any 20 ms period		-	0.5	W
$T_{stg}$	storage temperature			-40	150	$^\circ\text{C}$
$T_j$	junction temperature			-	150	$^\circ\text{C}$



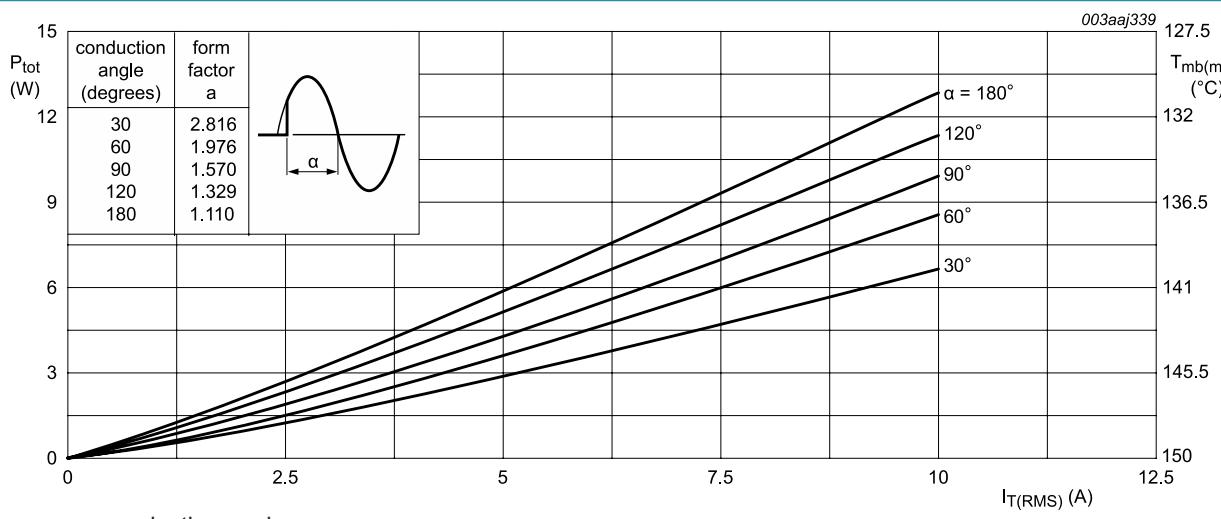


Fig. 3. Total power dissipation as a function of RMS on-state current; maximum values

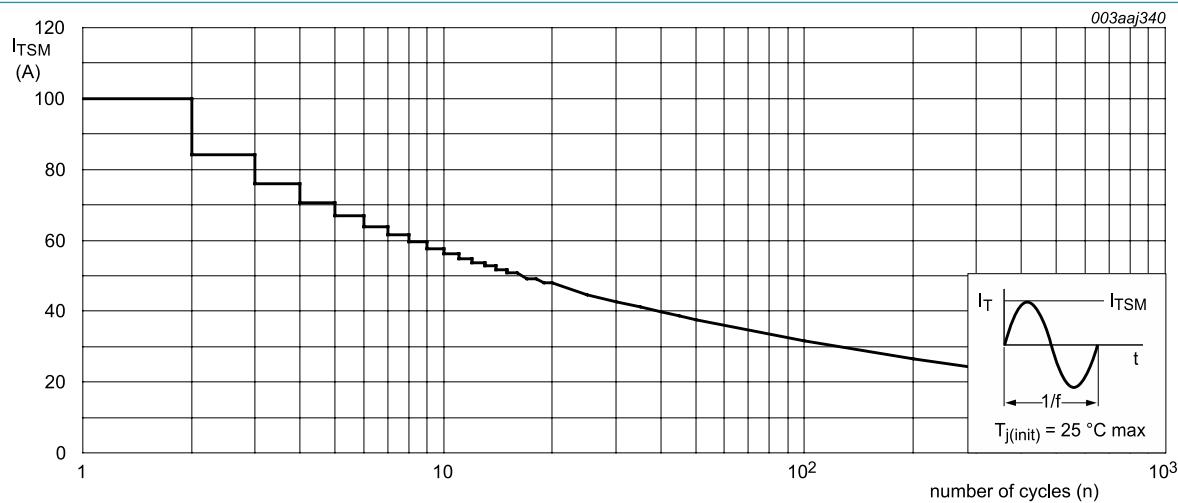


Fig. 4. Non-repetitive peak on-state current as a function of the number of sinusoidal current cycles; maximum values

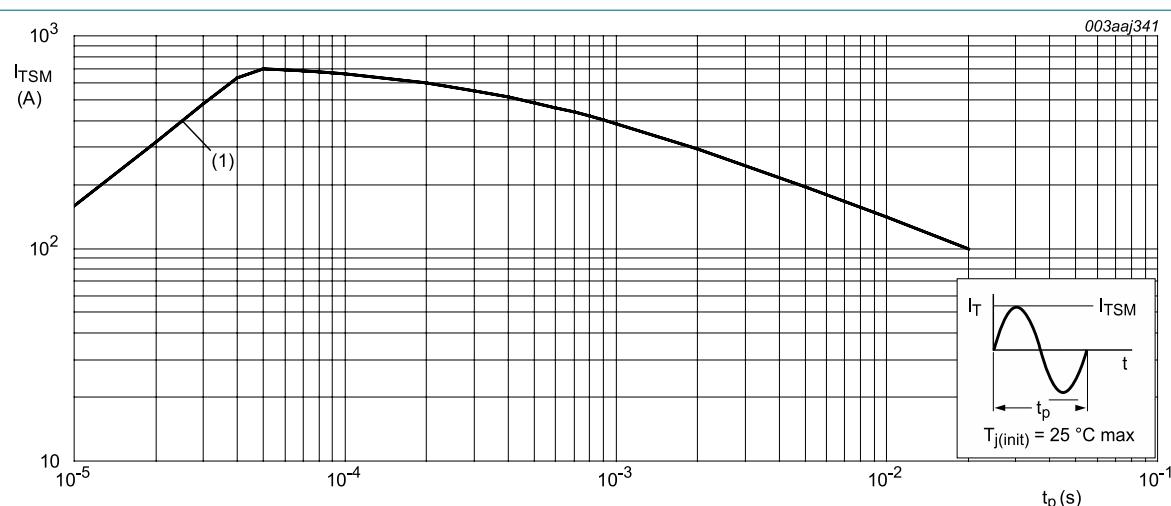


Fig. 5. Non-repetitive peak on-state current as a function of pulse duration; maximum values

## 8. Thermal characteristics

Table 5. Thermal characteristics

Symbol	Parameter	Conditions		Min	Typ	Max	Unit
$R_{th(j-mb)}$	thermal resistance from junction to mounting base	full cycle; <a href="#">Fig. 6</a>		-	-	1.5	K/W
		half cycle; <a href="#">Fig. 6</a>		-	-	2	K/W
$R_{th(j-a)}$	thermal resistance from junction to ambient	in free air		-	60	-	K/W

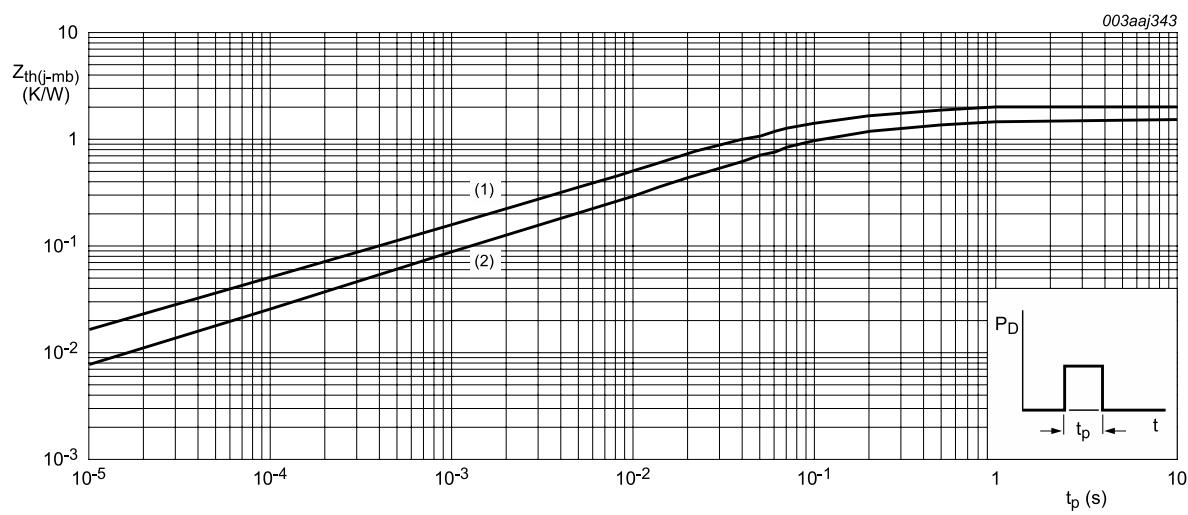
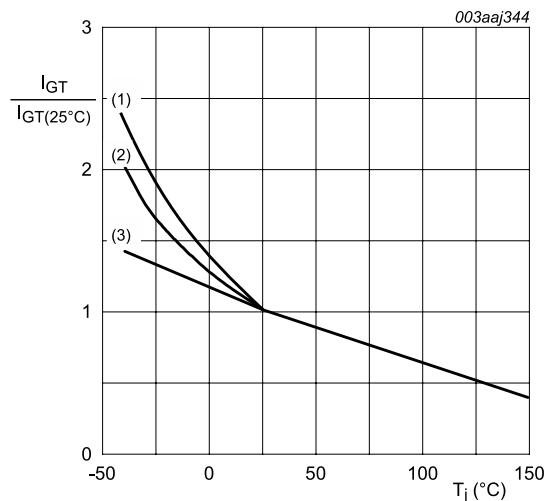


Fig. 6. Transient thermal impedance from junction to mounting base as a function of pulse duration

## 9. Characteristics

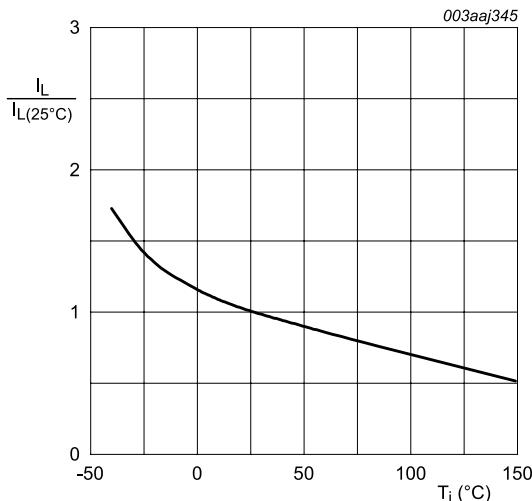
Table 6. Characteristics

Symbol	Parameter	Conditions		Min	Typ	Max	Unit
<b>Static characteristics</b>							
$I_{GT}$	gate trigger current	$V_D = 12 \text{ V}; I_T = 0.1 \text{ A}; T_2+ G+; T_j = 25^\circ\text{C}$ ; <a href="#">Fig. 7</a>		2	-	35	mA
		$V_D = 12 \text{ V}; I_T = 0.1 \text{ A}; T_2+ G-; T_j = 25^\circ\text{C}$ ; <a href="#">Fig. 7</a>		2	-	35	mA
		$V_D = 12 \text{ V}; I_T = 0.1 \text{ A}; T_2- G-; T_j = 25^\circ\text{C}$ ; <a href="#">Fig. 7</a>		2	-	35	mA
$I_L$	latching current	$V_D = 12 \text{ V}; I_G = 0.1 \text{ A}; T_2+ G+; T_j = 25^\circ\text{C}$ ; <a href="#">Fig. 8</a>		-	-	50	mA
		$V_D = 12 \text{ V}; I_G = 0.1 \text{ A}; T_2+ G-; T_j = 25^\circ\text{C}$ ; <a href="#">Fig. 8</a>		-	-	60	mA
		$V_D = 12 \text{ V}; I_G = 0.1 \text{ A}; T_2- G-; T_j = 25^\circ\text{C}$ ; <a href="#">Fig. 8</a>		-	-	50	mA
$I_H$	holding current	$V_D = 12 \text{ V}; T_j = 25^\circ\text{C}$ ; <a href="#">Fig. 9</a>		-	-	35	mA
$V_T$	on-state voltage	$I_T = 15 \text{ A}; T_j = 25^\circ\text{C}$ ; <a href="#">Fig. 10</a>		-	1.3	1.6	V
$V_{GT}$	gate trigger voltage	$V_D = 12 \text{ V}; I_T = 0.1 \text{ A}; T_j = 25^\circ\text{C}$ ; <a href="#">Fig. 11</a>		-	0.8	1	V
		$V_D = 400 \text{ V}; I_T = 0.1 \text{ A}; T_j = 150^\circ\text{C}$ ; <a href="#">Fig. 11</a>		0.25	0.4	-	V
$I_D$	off-state current	$V_D = 800 \text{ V}; T_j = 150^\circ\text{C}$		-	0.4	2	mA
<b>Dynamic characteristics</b>							
$dV_D/dt$	rate of rise of off-state voltage	$V_{DM} = 536 \text{ V}; T_j = 150^\circ\text{C}; (V_{DM} = 67\% \text{ of } V_{DRM})$ ; exponential waveform; gate open circuit		500	-	-	V/ $\mu$ s
$dl_{com}/dt$	rate of change of commutating current	$V_D = 400 \text{ V}; T_j = 150^\circ\text{C}; I_{T(RMS)} = 10 \text{ A}; dV_{com}/dt = 20 \text{ V}/\mu\text{s}$ ; (snubberless condition); gate open circuit		8	-	-	A/ms
		$V_D = 400 \text{ V}; T_j = 150^\circ\text{C}; I_{T(RMS)} = 10 \text{ A}; dV_{com}/dt = 10 \text{ V}/\mu\text{s}$ ; gate open circuit		13	-	-	A/ms
		$V_D = 400 \text{ V}; T_j = 150^\circ\text{C}; I_{T(RMS)} = 10 \text{ A}; dV_{com}/dt = 1 \text{ V}/\mu\text{s}$ ; gate open circuit		20	-	-	A/ms

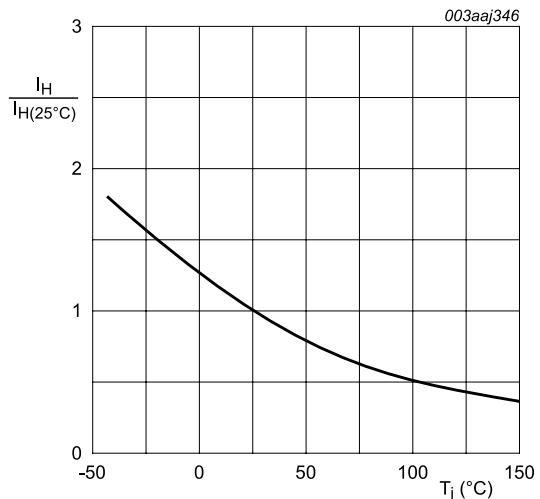


- (1) T2- G-
- (2) T2+ G-
- (3) T2+ G+

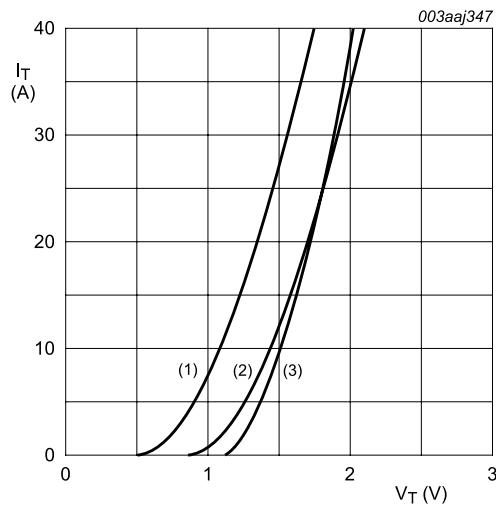
**Fig. 7. Normalized gate trigger current as a function of junction temperature**



**Fig. 8. Normalized latching current as a function of junction temperature**



**Fig. 9. Normalized holding current as a function of junction temperature**



$$V_o = 1.142 \text{ V}; R_s = 0.027 \Omega$$

(1) T<sub>j</sub> = 150 °C; typical values

(2) T<sub>j</sub> = 150 °C; maximum values

(3) T<sub>j</sub> = 25 °C; maximum values

**Fig. 10. On-state current as a function of on-state voltage**

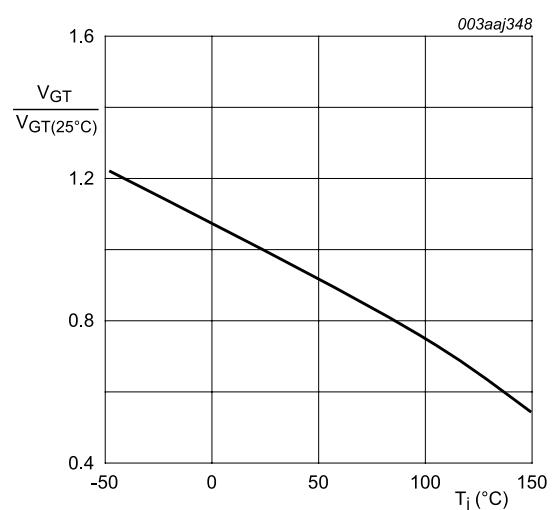
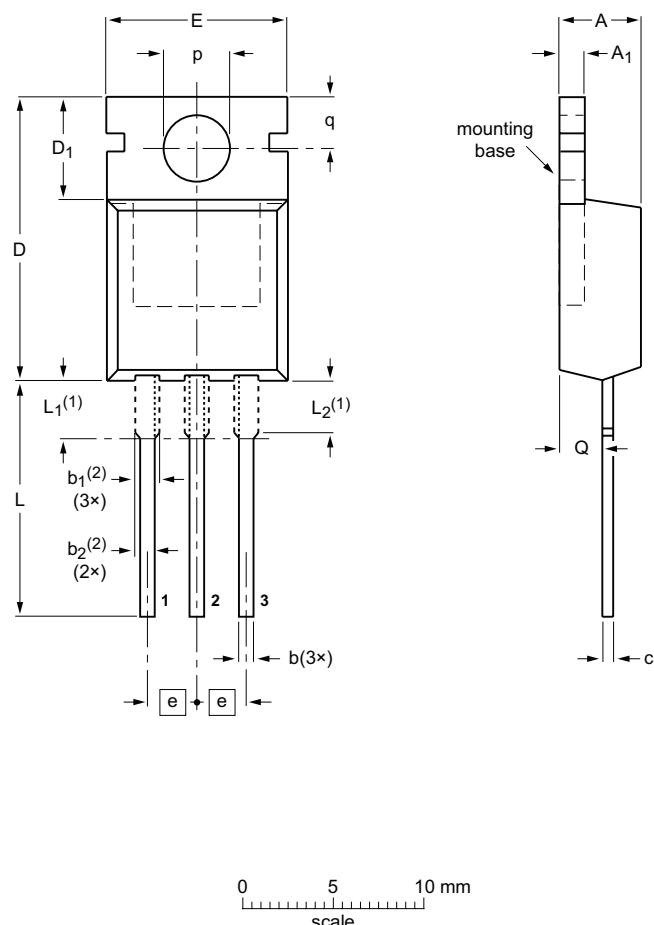


Fig. 11. Normalized gate trigger voltage as a function of junction temperature

## 10. Package outline

Plastic single-ended package; heatsink mounted; 1 mounting hole; 3-lead TO-220AB

SOT78



DIMENSIONS (mm are the original dimensions)

UNIT	A	A1	b	b <sub>1(2)</sub>	b <sub>2(2)</sub>	c	D	D <sub>1</sub>	E	e	L	L <sub>1(1)</sub>	L <sub>2(1)</sub> max.	p	q	Q
mm	4.7 4.1	1.40 1.25	0.9 0.6	1.6 1.0	1.3 1.0	0.7 0.4	16.0 15.2	6.6 5.9	10.3 9.7	2.54	15.0 12.8	3.30 2.79	3.0	3.8 3.5	3.0 2.7	2.6 2.2

Notes

1. Lead shoulder designs may vary.
2. Dimension includes excess dambar.

OUTLINE VERSION	REFERENCES					EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	JEITA				
SOT78		3-lead TO-220AB	SC-46				08-04-23 08-06-13